

Role of Annealing Atmosphere Towards Stoichiometry and Chemical Integrity of Solution-Processed MoS₂ Thin Films

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1. Introduction

Among various approaches, solution process is one of the quickest and simplest methods to produce MoS₂ thin films, compared to other techniques such as chemical vapor deposition (CVD), atomic layer deposition (ALD), and mechanical exfoliation [1-3]. However, their stoichiometry and chemical integrity are typically affected by sulfur vacancies (V_s) that serve as reactive sites for oxygen incorporation and cause degradation in device performance [4]. Annealing in sulfur vapor (S-vapor) represents a promising technique toward the restoration of stoichiometry through sulfur replenishing and concurrent oxidation suppression. Herein, we demonstrate the solution-based synthesis of MoS₂ films on Si₃N₄ surfaces with various precursor concentrations (5, 12, 16, 20, 25, and 30 mM) followed by annealing in argon (Ar) and sulfur vapor (S-vapor) at 700 °C. S-vapor annealed films achieved a near-ideal S/Mo ratio (~2:1) with significantly lower oxidation than Ar-annealed films, indicating the strong influence of annealing atmosphere on the stability of MoS₂.

2. Experimental Procedure

Molybdenum disulfide (MoS₂) films were prepared from a precursor solution via a single-step annealing in Ar and S-vapor atmospheres. The precursor solution was obtained by dissolving ammonium tetrathiomolybdate [(NH₄)₂MoS₄, 99.999%, Sigma Aldrich] in a solvent mixture of dimethylformamide (DMF), isopropanol (IPA), and ethanolamine with the 3:5:3 (v/v) ratio. The solution was stirred for 2 h, and spin-coated on clean Si₃N₄ surfaces at 500 rpm for 10 s and 3000 rpm for 30 s. The Si₃N₄ surfaces were treated with 0.5% HF for 60 s followed by rinse with DI water. The films were pre-annealed at 180 °C for 30 min and annealed at 700 °C for 1 h under 1 slm Ar flow using a lamp annealing system. S-vapor annealing procedures are demonstrated in Fig. 1. The fabricated MoS₂ films were characterized using transmission electron microscopy (TEM), Raman spectroscopy, x-ray photoelectron spectroscopy (XPS) and thermal desorption spectroscopy (TDS) respectively.

3. Results and Discussion

To assess the stoichiometry and sulfur vacancy (V_s) of the MoS₂ films, X-ray photoelectron spectroscopy (XPS) measurements were performed on both the surface and after 15 s etching, as illustrated in Fig. 2. At 5 mM, both films show sulfur deficiency (S/Mo ~2:1), but Ar-annealed films (Fig. 2a) remain sub-stoichiometric across all concentrations. In contrast, S-vapor annealed films (Fig. 2b) approach the ideal 2:1 ratio with increasing concentration and achieve homogeneous stoichiometry above 12 mM. These results confirm the effectiveness of S-vapor annealing in mitigating sulfur vacancies [5], despite minor surface oxidation upon air exposure.

The Mo⁶⁺/Mo⁴⁺ ratios of Ar and S-vapor annealed MoS₂ films were obtained from the Mo 3d XPS spectra (Fig. 3). Ar-annealed MoS₂ films (Fig. 3a) undergo significant oxidation, with Mo⁶⁺/Mo⁴⁺ ratios reaching a maximum at ~0.45 around 16 mM and persisting even after etching, indicating interfacial defects and oxygen incorporation. In contrast, S-vapor annealing keeps the ratio below 0.2 (slightly higher at the surface), yielding stoichiometric and chemically stable films above 12 mM as illustrated in Fig. 3b. These results confirm the superior oxidation resistance of S-vapor annealed MoS₂. Sulfur vacancies in MoS₂ strongly affect its electronic properties and also promote environmental degradation through oxidation. To investigate the impact of these vacancies and the subsequent adsorption of O₂ and H₂O molecules, density functional theory (DFT) calculations were performed as shown in Fig. 4. PDOS analysis shows that pristine MoS₂ with a band gap (E_g) of 1.7 eV, has a S-3p dominated valence band and a Mo-4d dominated conduction band with no mid-gap states. Introducing a sulfur vacancy reduces the band gap to 1.3 eV and creates Mo 4d defect states near the Fermi level. O₂ adsorption slightly recovers the gap (1.5 eV) but leaves residual states, indicating poor passivation. In contrast, H₂O adsorption restores the gap to 1.74 eV, effectively suppressing defect states and providing better passivation.

4. Conclusions

In conclusion, S-vapor annealing is essential for repairing sulfur vacancies, suppressing oxidation, and achieving near-stoichiometric, crystalline MoS₂ films. This post-synthesis treatment offers a reliable route to structurally and chemically stable MoS₂ for future electronic applications.

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References

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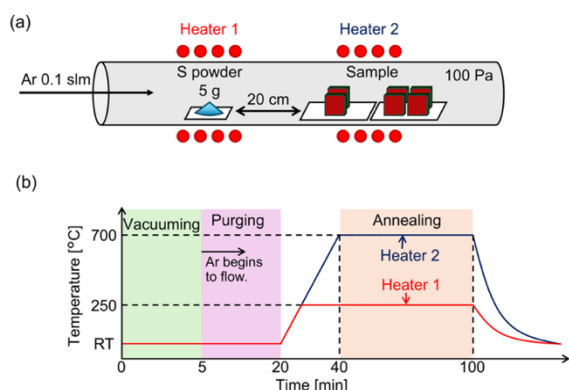


Fig. 1: (a) Schematic of the two-zone furnace setup used for sulfur annealing of MoS₂ films and (b) Temperature vs time profile of annealing process.

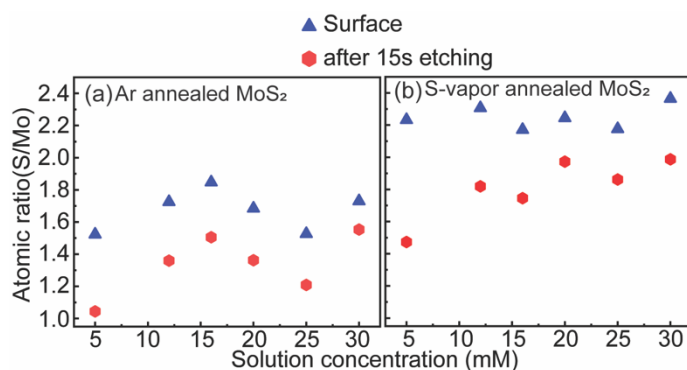


Fig. 2: Sulfur-to-molybdenum (S/Mo) atomic ratio of MoS₂ films as a function of precursor concentration, extracted from XPS of Mo 3d: (a) Ar-annealed and (b) S vapor-annealed films at 700 °C.

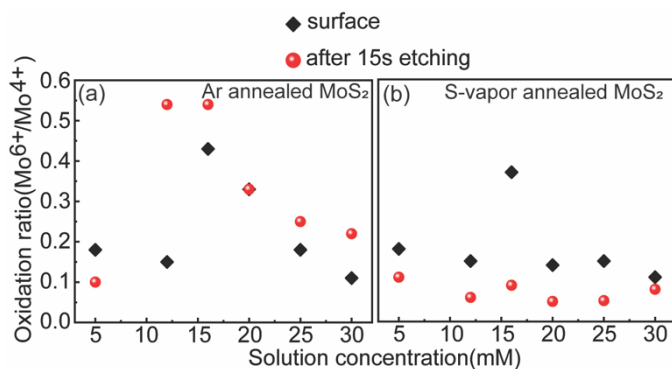


Fig. 3: Mo⁶⁺/Mo⁴⁺ ratio as a function of solution concentration, extracted from Mo 3d XPS spectra of MoS₂ films grown on Si₃N₄ surfaces using (a) Ar annealing and (b) S vapor annealing at 700 °C.

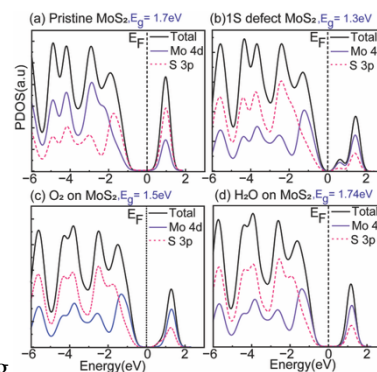


Fig. 4: PDOS of MoS₂ films under different conditions: (a) Pristine MoS₂ (b) Sulfur defect (1S) defect MoS₂ (c) O₂ adsorbed MoS₂ and H₂O adsorbed MoS₂ respectively.